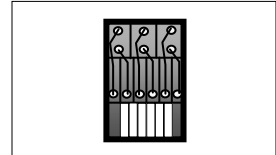


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Ericsson GSM/LTE Multi-mode Baseband Unit KDU 137 624/3 R2A Model DUS 31 01

August 2014



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